at least one ceramic paste present in film-form; and

blunting edges of the [sensing element] composite arrangement before sintering to increase a thermal shock resistance of the sensing element.

14. (Amended) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the [sensing element] composite arrangement by shaping.

- 15. (Amended) The method according to claim 14, wherein the step of blunting the edges of the [sensing element] composite arrangement further includes the step of blunting the edges of the [sensing element] composite arrangement by stamping.
- 16. (Amended) The method according to claim 13, further comprising the step of: introducing a profile into a stamping apparatus for pre-pressing a laminate construction of unsintered films of the [sensing element] composite arrangement.
- 19. (Amended) The method according to claim 13, wherein the step of blunting the edges of the [sensing element] composite arrangement further includes the step of blunting the edges of the [sensing element] composite arrangement using a laser treatment.
- 20. (Amended) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the [sensing element] composite arrangement using an excimer laser having definable masking.
- 21. (Amended) The method according to claim 13, wherein the step of blunting includes the step of treating sectioned [sensing elements] composite arrangements with a laser, the sectioned [sensing elements] composite arrangements having a composition construction of green films.
- 22. (Amended) The method according to claim 21, further comprising the step of: sectioning the [sensing element] composite arrangement from a wafer,